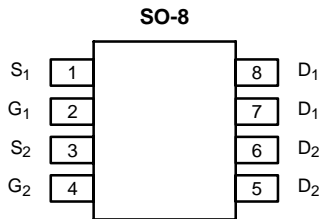


## Dual N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY		
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)
30	0.022 @ V <sub>GS</sub> = 10 V	7.5
	0.030 @ V <sub>GS</sub> = 4.5 V	6.5

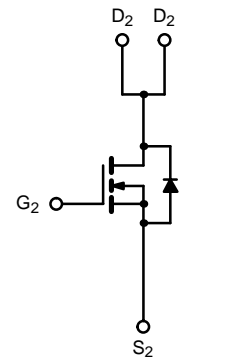
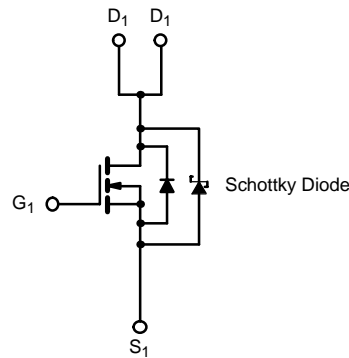
SCHOTTKY PRODUCT SUMMARY		
V <sub>DS</sub> (V)	V <sub>SD</sub> (V) Diode Forward Voltage	I <sub>F</sub> (A)
30	0.50 V @ 1.0 A	2.0

**LITTLE FOOT PLUS™**



Top View

Ordering Information: Si4834DY  
Si4834DY-T1 (with Tape and Reel)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)				
Parameter	Symbol	10 secs	Steady State	Unit
Drain-Source Voltage	V <sub>DS</sub>	30		V
Gate-Source Voltage	V <sub>GS</sub>	± 20		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	I <sub>D</sub>	T <sub>A</sub> = 25 °C	7.5	5.7
		T <sub>A</sub> = 70 °C	6.0	4.6
Pulsed Drain Current	I <sub>DM</sub>	30		A
Continuous Source Current (Diode Conduction) <sup>a</sup>	I <sub>S</sub>	1.7	0.9	
Maximum Power Dissipation <sup>a</sup>	P <sub>D</sub>	T <sub>A</sub> = 25 °C	2.0	1.1
		T <sub>A</sub> = 70 °C	1.3	0.7
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	MOSFET		Schottky		Unit
		Typ	Max	Typ	Max	
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>thJA</sub>	t ≤ 10 sec	52	62.5	53	62.5
		Steady-State	93	110	93	110
Maximum Junction-to-Foot (Drain)	R <sub>thJC</sub>	35	40	35	40	°C/W

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

<b>MOSFET SPECIFICATIONS (<math>T_J = 25^\circ\text{C}</math> UNLESS OTHERWISE NOTED).</b>						
Parameter	Symbol	Test Condition	Min	Typ <sup>a</sup>	Max	Unit
<b>Static</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.8			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$	Ch-1		100	$\mu\text{A}$
			Ch-2		1	
		$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	Ch-1		2000	
			Ch-2		15	
On-State Drain Current <sup>b</sup>	$I_{D(on)}$	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			A
Drain-Source On-State Resistance <sup>b</sup>	$r_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		0.018	0.022	$\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 6.5 \text{ A}$		0.024	0.030	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15 \text{ V}, I_D = 7.5 \text{ A}$		22		S
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	$I_S = 1 \text{ A}, V_{GS} = 0 \text{ V}$	Ch-1	0.47	0.5	V
			Ch-2	0.8	1.2	
<b>Dynamic<sup>a</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		13	20	nC
Gate-Source Charge	$Q_{gs}$			2		
Gate-Drain Charge	$Q_{gd}$			2.7		
Gate Resistance	$R_g$		0.5	1.9	3.2	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15 \text{ V}, R_L = 15 \Omega$ $I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 6 \Omega$		8	16	ns
Rise Time	$t_r$			10	20	
Turn-Off Delay Time	$t_{d(off)}$			21	40	
Fall Time	$t_f$			10	20	
Source-Drain Reverse Recovery Time	$t_{rr}$	$I_F = 1.7 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	Ch-1	32	70	
			Ch-2	40	80	

## Notes

- a. Guaranteed by design, not subject to production testing.  
 b. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

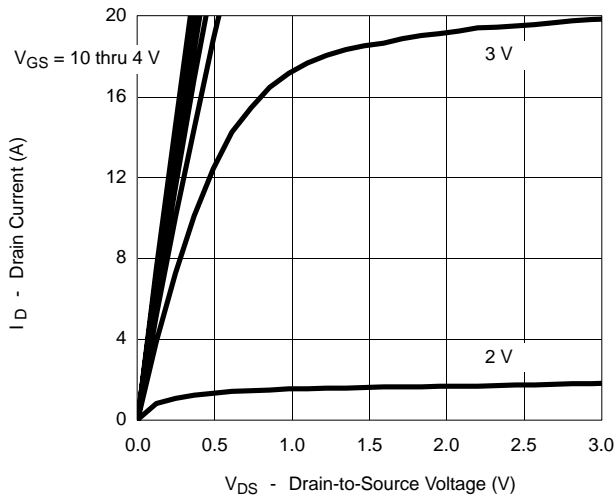
<b>SCHOTTKY SPECIFICATIONS (<math>T_J = 25^\circ\text{C}</math> UNLESS OTHERWISE NOTED)</b>						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage Drop	$V_F$	$I_F = 1.0 \text{ A}$		0.47	0.50	V
		$I_F = 1.0 \text{ A}, T_J = 125^\circ\text{C}$		0.36	0.42	
Maximum Reverse Leakage Current	$I_{rm}$	$V_r = 30 \text{ V}$		0.004	0.100	mA
		$V_r = 30 \text{ V}, T_J = 100^\circ\text{C}$		0.7	10	
		$V_r = -30 \text{ V}, T_J = 125^\circ\text{C}$		3.0	20	
Junction Capacitance	$C_T$	$V_r = 10 \text{ V}$		50		pF



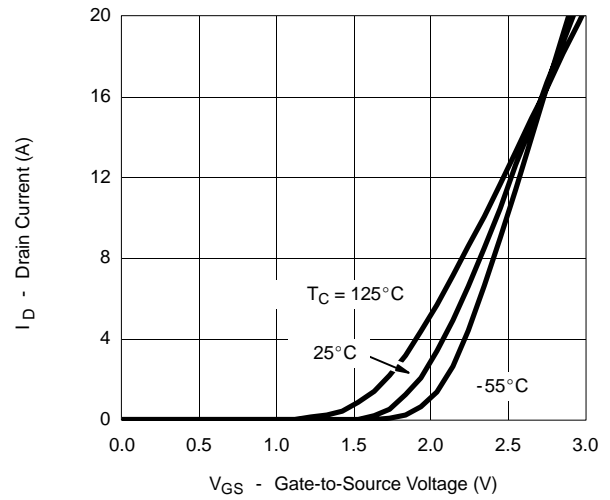
**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**

**MOSFET**

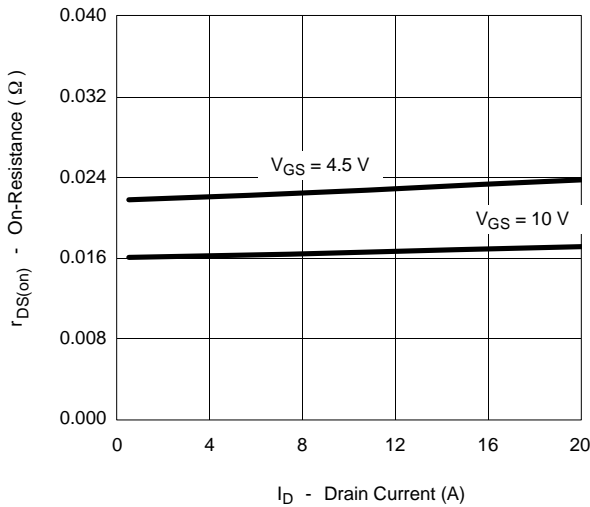
**Output Characteristics**



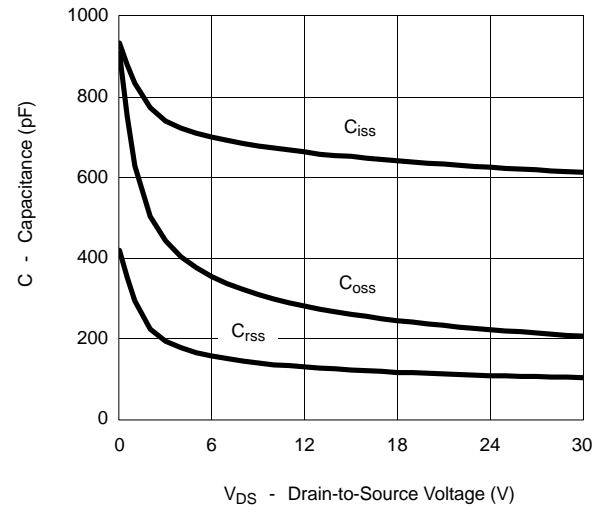
**Transfer Characteristics**



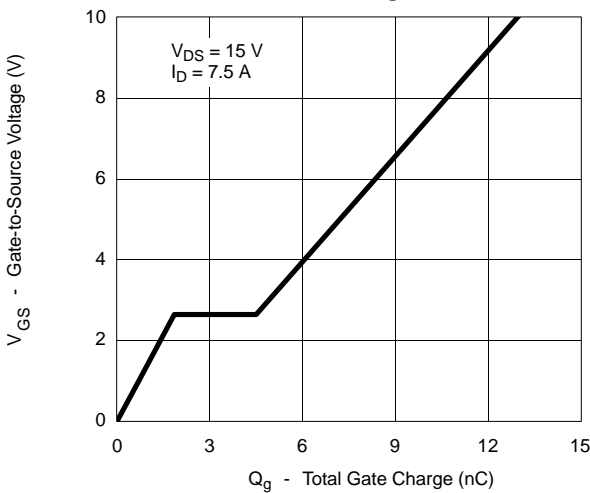
**On-Resistance vs. Drain Current**



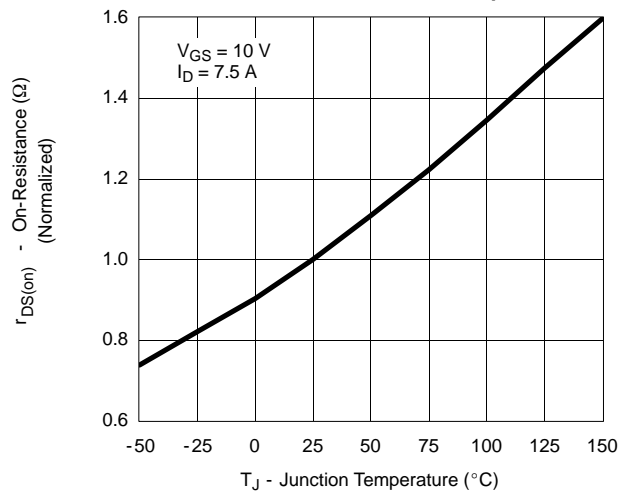
**Capacitance**



**Gate Charge**



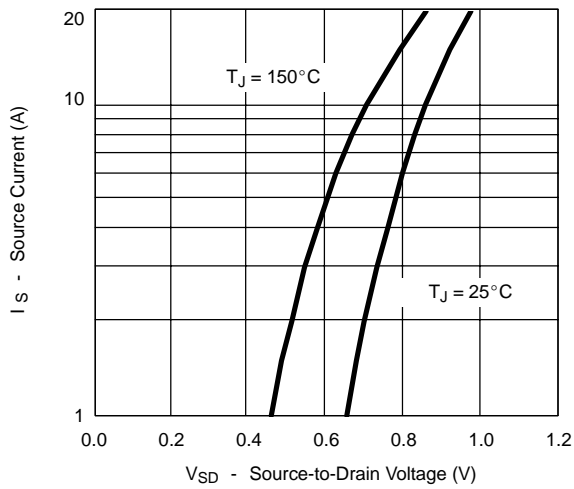
**On-Resistance vs. Junction Temperature**



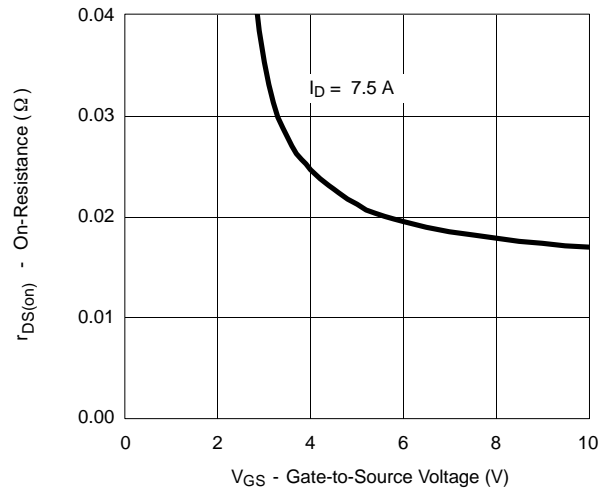
**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**

**MOSFET**

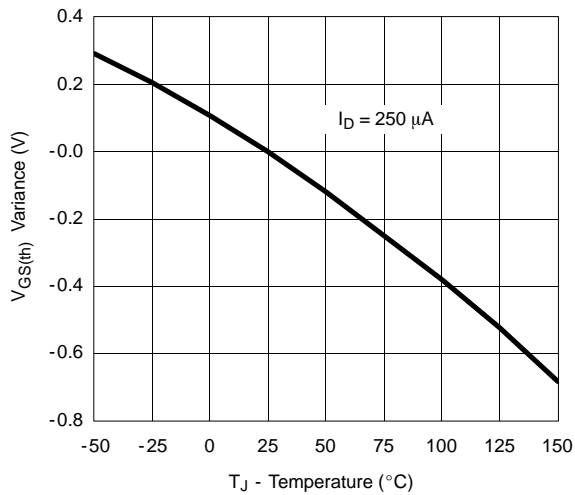
Source-Drain Diode Forward Voltage



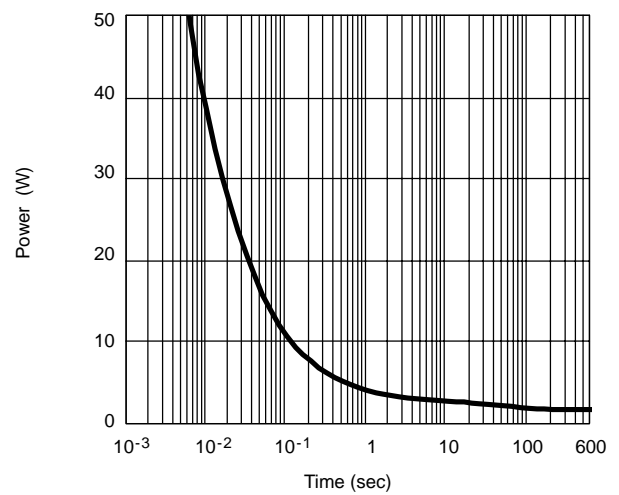
On-Resistance vs. Gate-to-Source Voltage



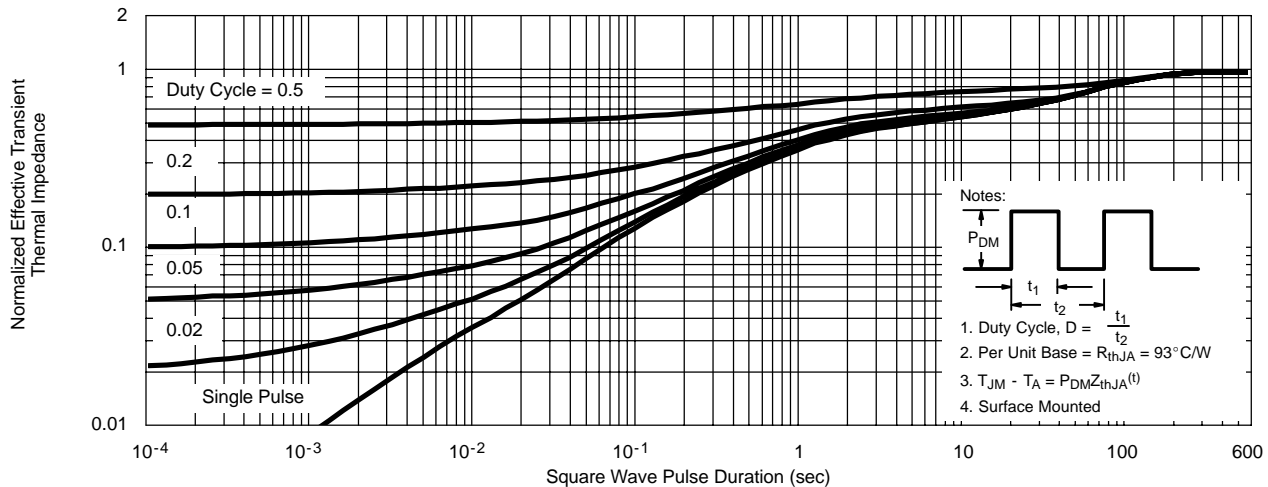
Threshold Voltage



Single Pulse Power



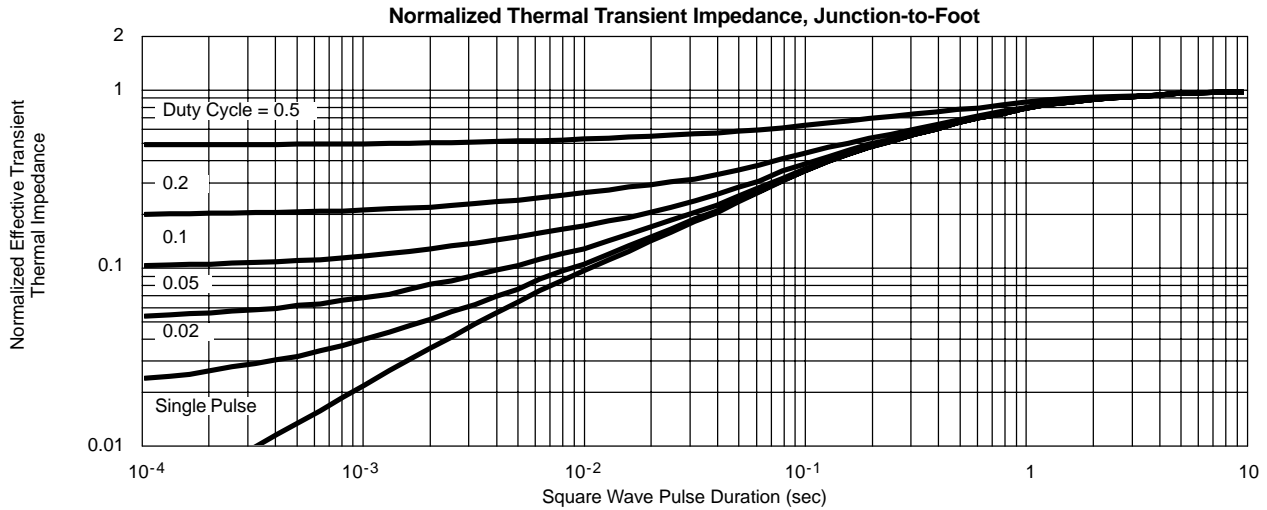
Normalized Thermal Transient Impedance, Junction-to-Ambient





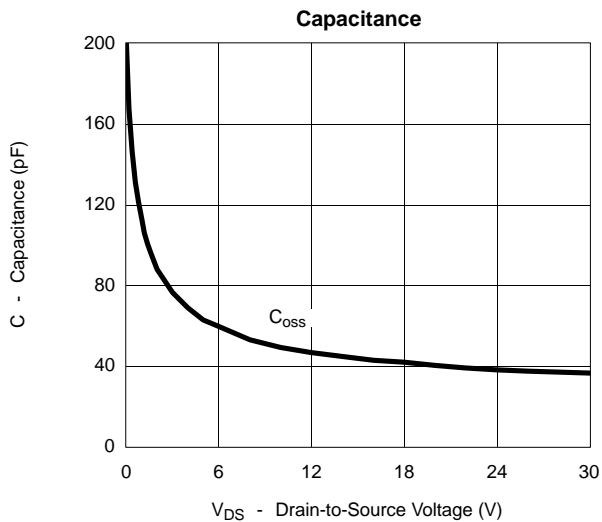
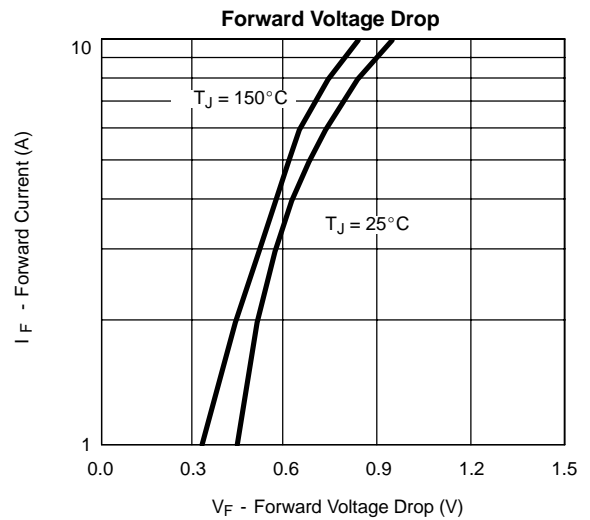
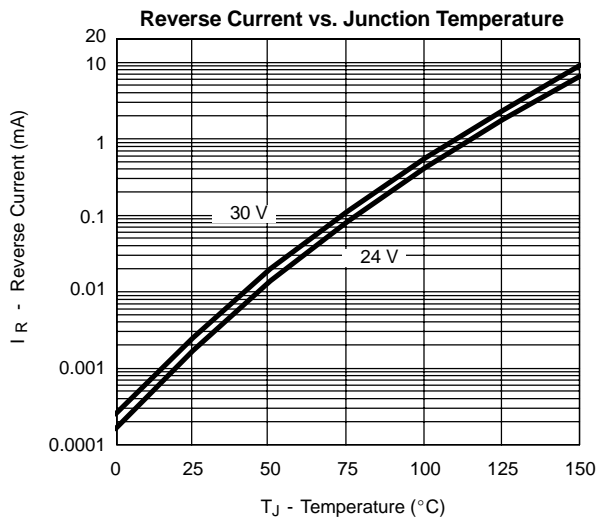
**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**

**MOSFET**



**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**

**SCHOTTKY**





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